



VMDSEMI

**VSXX065R18BNA**

**Datasheet**

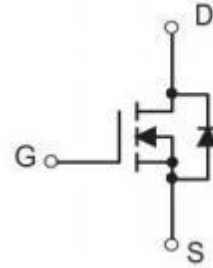


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## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
650V	1.8Ω@10V	2.7A

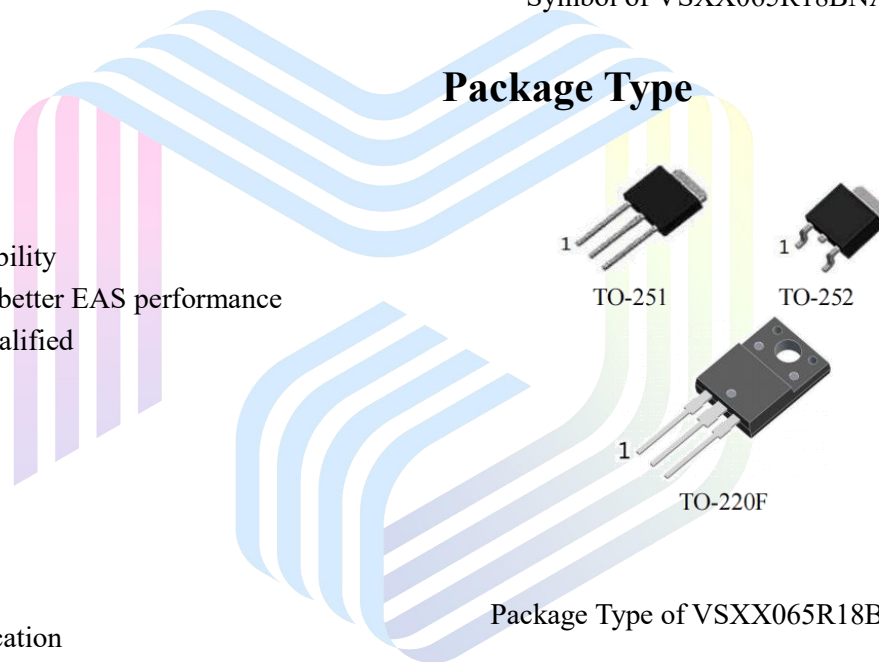


Symbol of VSXX065R18BNA

## Features

- Ultra Low  $R_{DS(ON)}$
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified

## Package Type



Package Type of VSXX065R18BNA

## Application

- High Voltage Application
- LED Lighting Power

## Ordering Information

Product Name	Package
VSTJ065R18BNA	TO-251
VSTL065R18BNA	TO-252
VSTD065R18BNA	TO-220F

**Absolute Maximum Ratings**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	650	V
Gate-Source Voltage	$V_{GSS}$	±20	V
Gate-Source Voltage (AC, $f > 1\text{Hz}$ )		±30	
Continuous Drain Current $T_C = 25\text{ °C}$	$I_D$	2.7	A
Continuous Drain Current $T_C = 125\text{ °C}$		1.2	
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	8.1	
Continuous diode forward current	$I_S$	2.7	
Diode pulsed current	$I_{S,PULSE}$	8.1	
Single Pulsed Avalanche Energy <sup>Note3</sup>	$E_{AS}$	32	mJ
Avalanche Energy, Repetitive <sup>Note2</sup>	$E_{AR}$	0.03	
Avalanche Current, Repetitive <sup>Note2</sup>	$I_{AR}$	0.1	A
Operating Junction Temperature	$T_J$	150	°C



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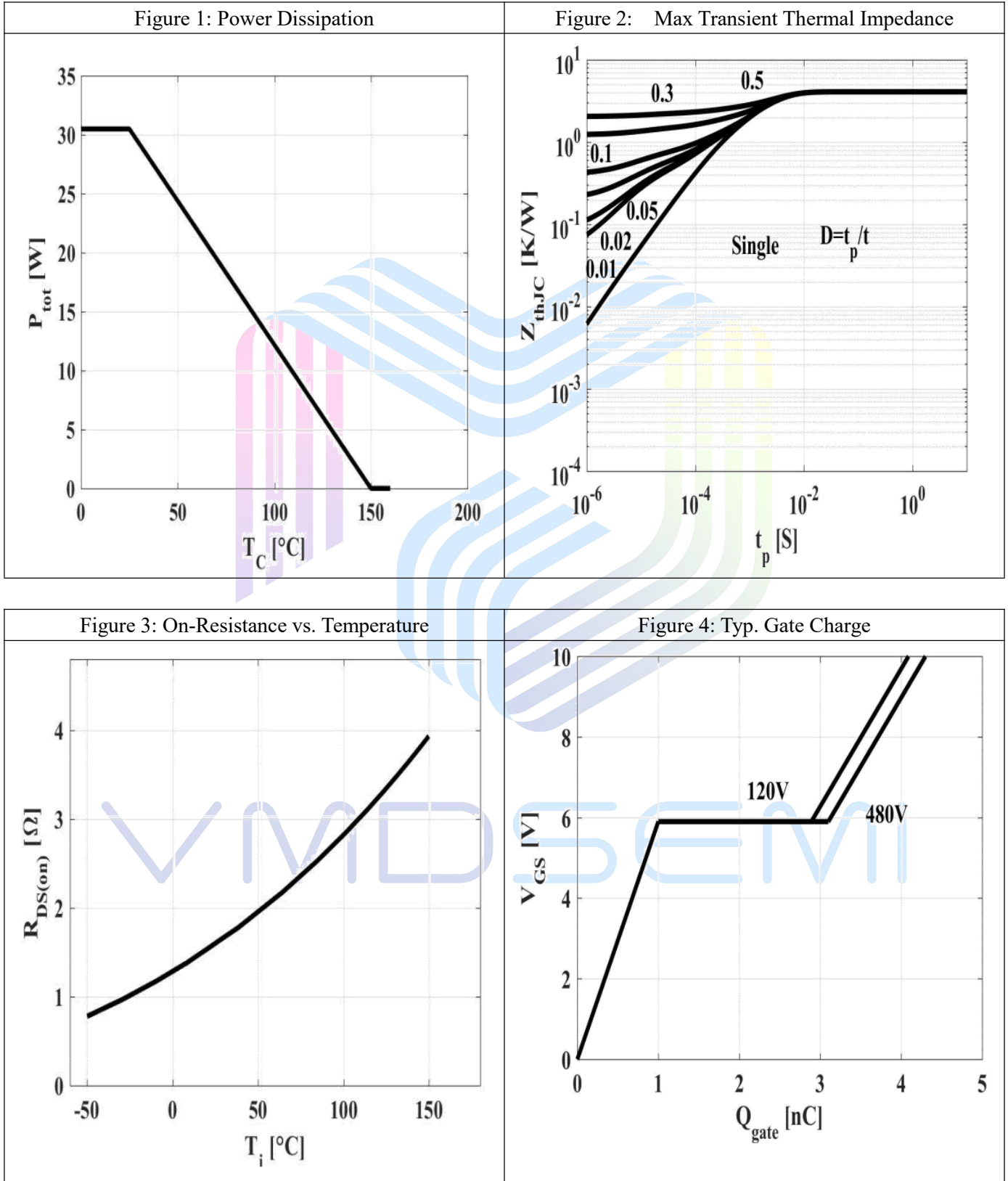
**1.8Ω, 650V, N-Channel Power MOSFET**
**VSXX065R18BNA**
**Electrical Characteristics** ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

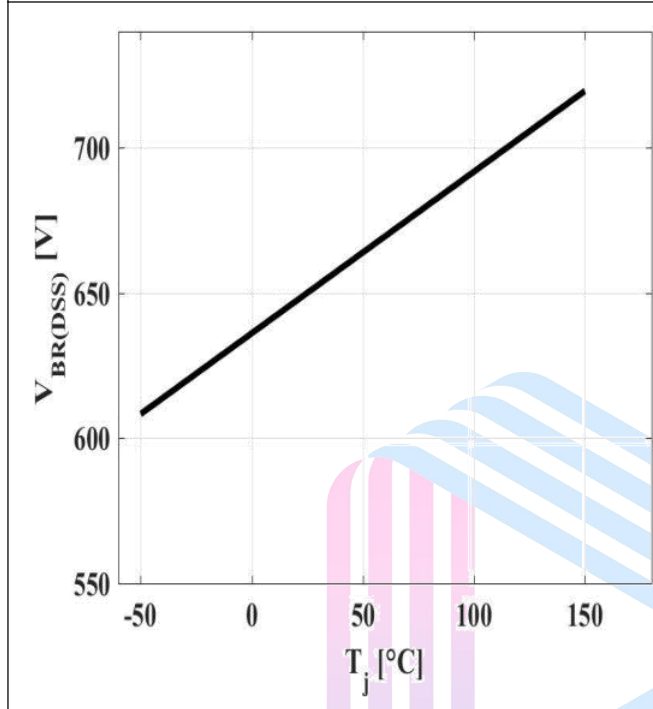
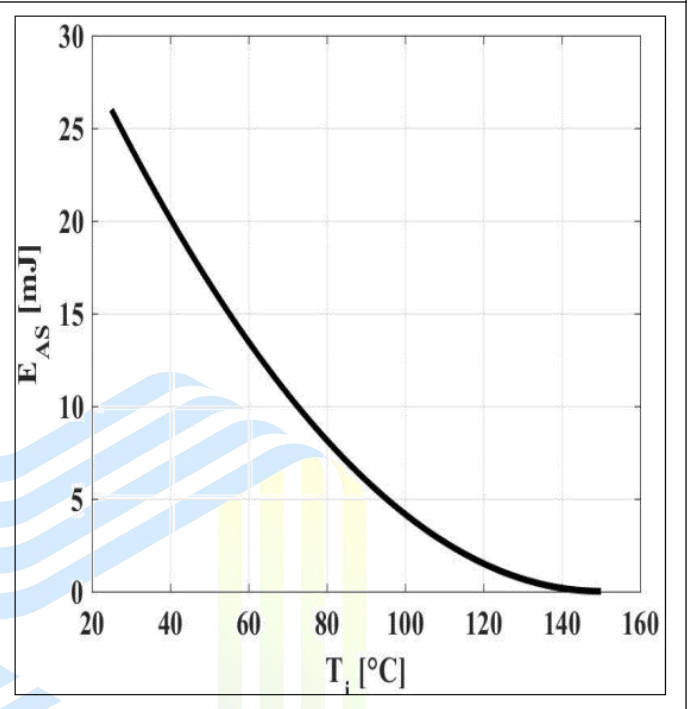
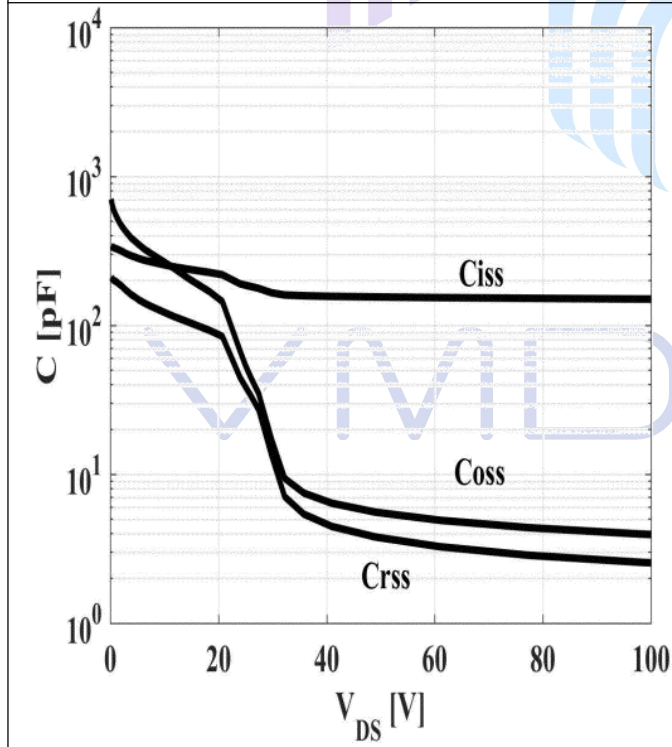
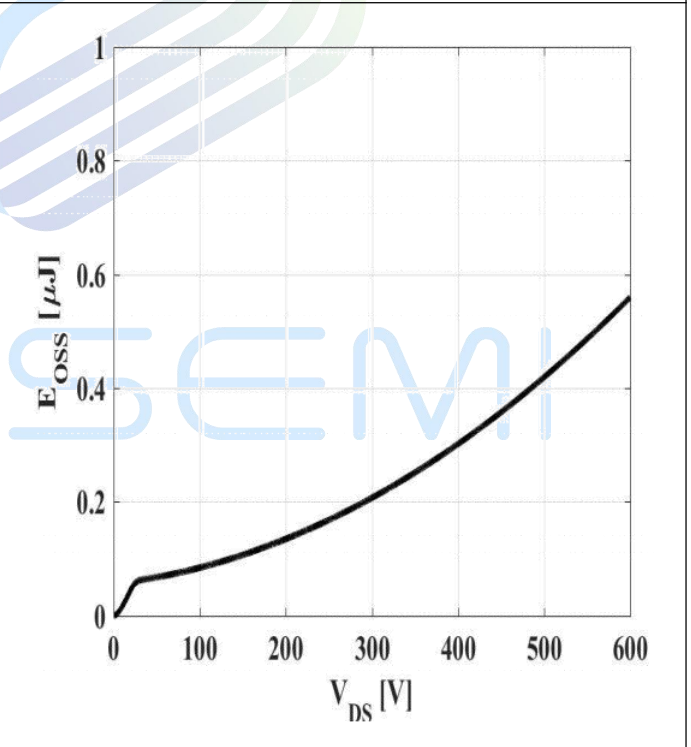
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b> <sup>Note1</sup>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	650			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=650V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSSF}$	$V_{GS}=20V, V_{DS}=0V$			100	nA
	$I_{GSSR}$	$V_{GS}=-20V, V_{DS}=0V$			-1	$\mu A$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.7	3.5	4.3	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=1.3A$		1.5	1.8	$\Omega$
<b>Dynamic Characteristics</b> <sup>Note2</sup>						
Input Capacitance	$C_{ISS}$	$V_{DS}=50V$		160		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		9		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		4		pF
Gate Resistance	$R_g$	$f=1MHz, \text{open drain}$		8		$\Omega$
Total Gate Charge	$Q_g$	$V_{DS}=480V$ $V_{GS}=0 \text{ to } 10V$ $I_D=1.3A$		4.3		nC
Gate-Source Charge	$Q_{gs}$			1.0		
Gate-Drain Charge	$Q_{gd}$			2.1		
Gate Plateau Voltage	$V_{plateau}$			5.9		V
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note2</sup>	$V_{SD}$	$V_{GS}=0V, I_S=1.3A$		0.84	1.1	V

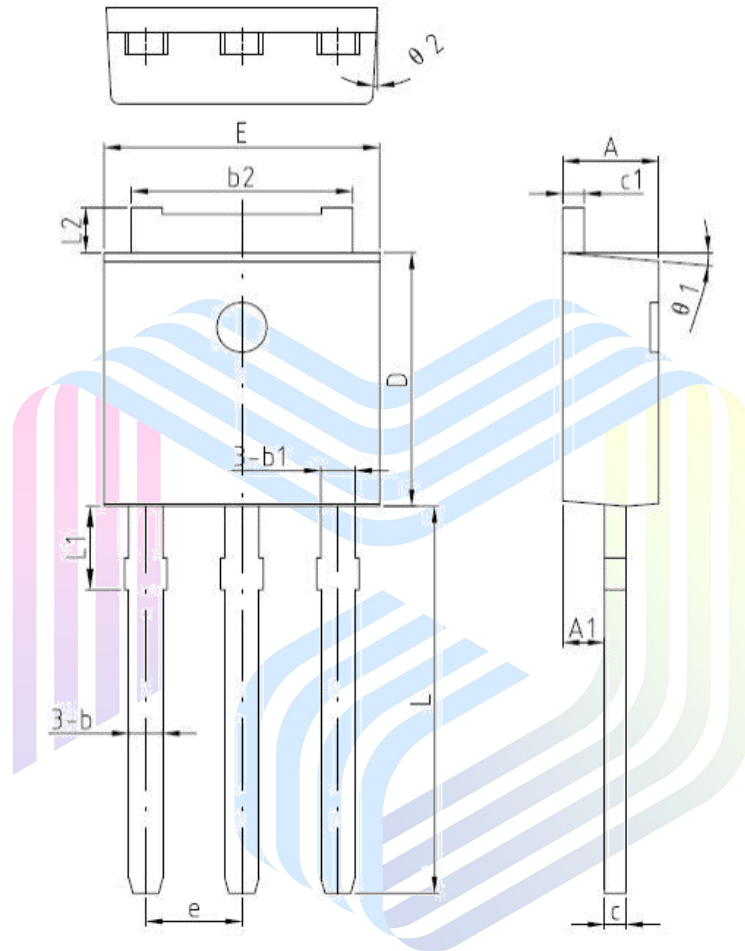
**Notes :**

- Absolute maximum ratings are those values beyond which the device could be permanently damaged  
Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS}=0.1A, V_{DD}=60V, R_G=25\Omega, \text{Starting } T_J=25^\circ\text{C}$

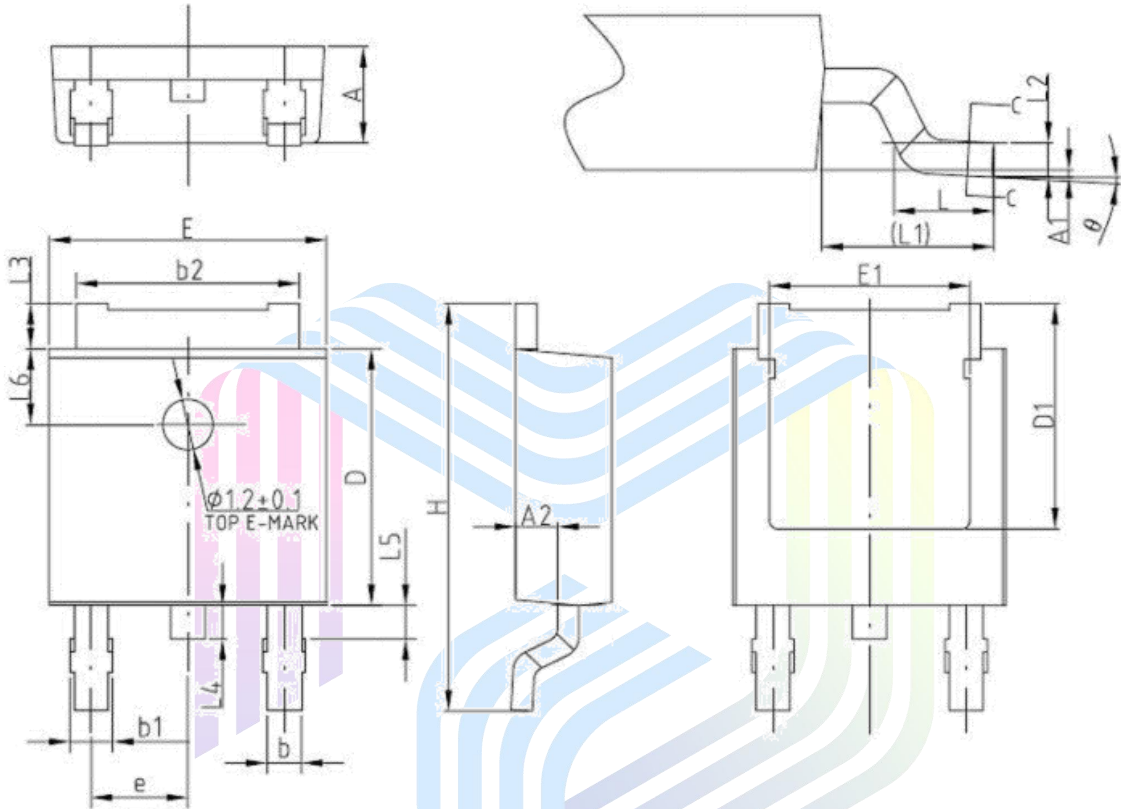


**Typical Performance Characteristics**


**Figure 5: Drain Source Breakdown Voltage**

**Figure 6: Avalanche Energy**

**Figure 7: Typ. Capacitance**

**Figure 8: Coss Stored Energy**


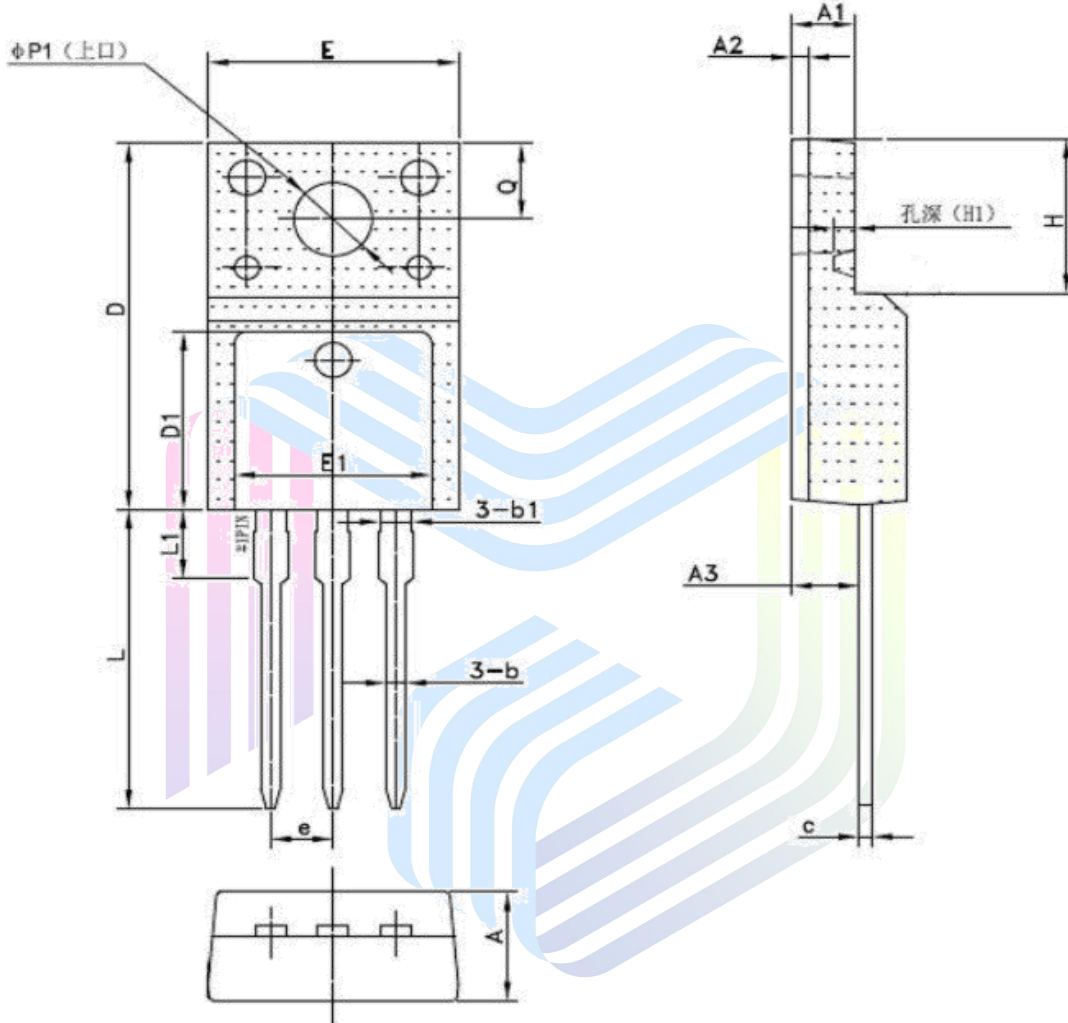
**Mechanical Dimensions:**
**TO-251 Package Information**


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	2.20	2.30	2.40
A1	0.90	1.01	1.17
b	0.50	-	0.91
b1	-	0.81	-
b2	5.13	5.33	5.46
c	0.46	0.50	0.60
c1	0.46	0.50	0.60
D	5.95	6.10	6.25
E	6.45	6.60	6.75
e	2.286(BSC)		
L	9.00	9.30	9.60
L1	-	2.00	-
L2	0.90	-	1.25
θ1	-	5°	-
θ2	-	3°	-

**Mechanical Dimensions:**
**TO-252 Package Information**


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	2.20	2.30	2.40
A1	0	-	0.10
A2	0.90	1.00	1.17
b	0.70	0.76	0.90
b1	0.77	-	1.10
b2	5.13	5.33	5.46
c	0.45	-	0.60
D	5.95	6.10	6.25
D1	-	5.30	-
E	6.45	6.60	6.75
E1	-	4.80	-
e	2.286(BSC)		
H	9.70	10.10	10.40
L	1.25	1.50	1.75
L1	-	2.90	-
L2	-	0.51	-
L3	0.90	-	1.25
L4	-	0.80	-
L5	-	1.00	-
L6	-	1.80	-
θ	0°	-	8°



**Mechanical Dimensions:**
**TO-220F Package Information**


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.30	4.70	4.90
A1	2.34	2.54	2.90
A2	-	0.70	-
A3	2.56	2.76	2.96
b	0.55	-	0.95
b1	-	1.28	-
c	0.42	0.50	0.70
D	14.70	-	16.07
D1	-	7.70	-
E	9.96	10.16	10.36
E1	-	8.00	-
e	2.54(BSC)		
H	-	6.70	-
(H1)	-	(0.81)	-
L	12.48	12.98	13.50
L1	-	2.93	-
ΦP1	-	3.18	-
Q	2.90	3.30	3.50

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